

Solid State Relay OCMOS FET PS7200A-1A

4-PIN SOP, 3.0 pF LOW OUTPUT CAPACITANCE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7200A-1A is a low output capacitance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low $C \times R$, low output capacitance, and low off-state leakage current.

FEATURES

- Low $C \times R$ ($C \times R = 30 \text{ pF} \cdot \Omega$)
- Low output capacitance (Cout = 3.0 pF TYP.)
- Low off-state leakage current (ILoff = 0.1 nA TYP.)
- High-speed turn-on time (ton = 0.01 ms TYP.)
- 1 channel type (1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- · Low offset voltage
- Ordering number of taping product : PS7200A-1A-E3, E4: 900 pcs/reel

: PS7200A-1A-F3, F4: 3 500 pcs/reel

<R> • Pb-Free product

- Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8241/8242
 - CSA approved: No. CA 101391

APPLICATIONS

Measurement equipment

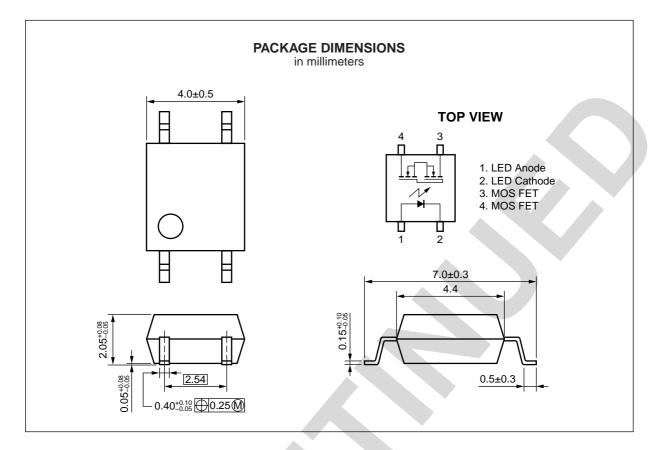
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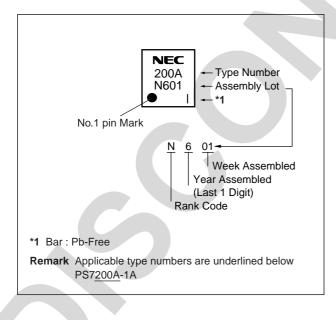
The mark <R> shows major revised points.

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The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.



<R> MARKING EXAMPLE (LASER MARKING)



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7200A-1A	PS7200A-1A-A	Pb-Free	Magazine case 100 pcs	Standard products	PS7200A-1A
PS7200A-1A-E3	PS7200A-1A-E3-A		Embossed Tape 900 pcs/reel	(UL, BSI, CSA	
PS7200A-1A-E4	PS7200A-1A-E4-A			approved)	
PS7200A-1A-F3	PS7200A-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7200A-1A-F4	PS7200A-1A-F4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW
	Peak Forward Current *1	IFP	1	A
MOS FET	Break Down Voltage	VL	40	V
	Continuous Load Current	١L	100	mA
	Pulse Load Current ^{*2} (AC/DC Connection)	Ilp	200	mA
	Power Dissipation	PD	100	mW
Isolation Voltage *3		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	150	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

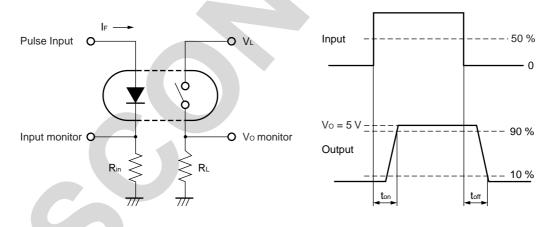
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	Ir	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 40 V		0.1	100	nA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		3.0		pF
Coupled	LED On-state Current	IFon	I∟ = 100 mA			2.0	mA
	On-state Resistance	Ron1	I⊧ = 10 mA, I∟ = 10 mA		9.3	12	Ω
		Ron2	I_{F} = 10 mA, I_{L} = 100 mA, $t \leq$ 10 ms				
	Turn-on Time ^{*1, 2}	ton	I_F = 10 mA, Vo = 5 V, RL = 500 Ω,		0.01	0.5	ms
	Turn-off Time ^{*1, 2}	toff	PW ≥ 10 ms		0.07	0.2	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		0.5		pF

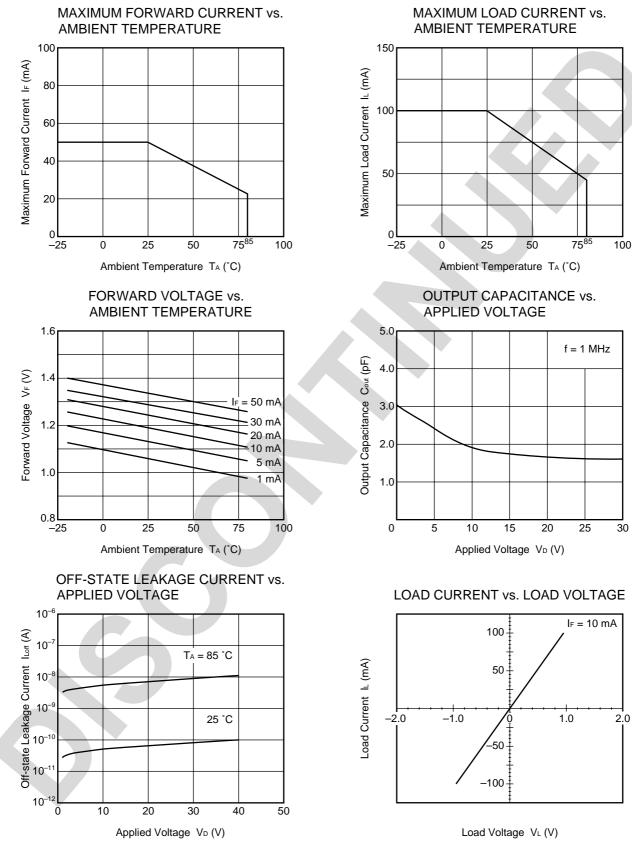
*1 Test Circuit for Switching Time



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*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
 Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

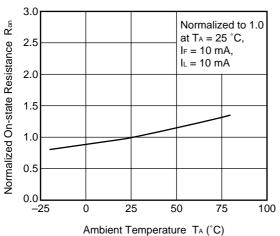


Remark The graphs indicate nominal characteristics.

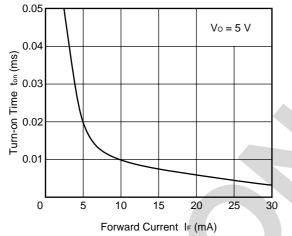
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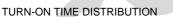
2.0

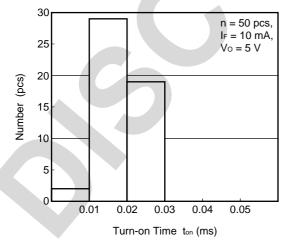






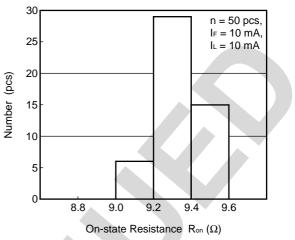




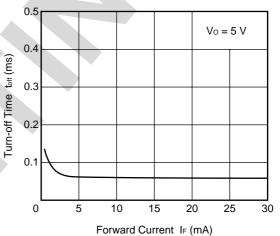


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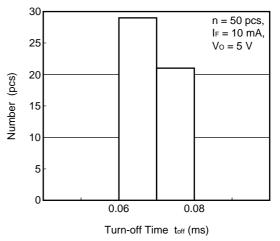
ON-STATE RESISTANCE DISTRIBUTION

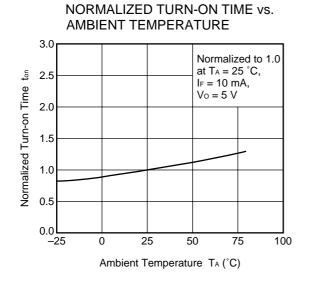


TURN-OFF TIME vs. FORWARD CURRENT

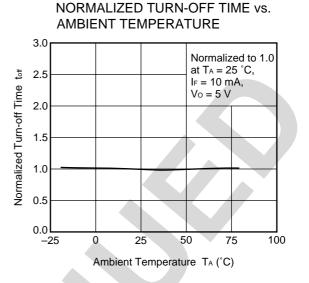


TURN-OFF TIME DISTRIBUTION



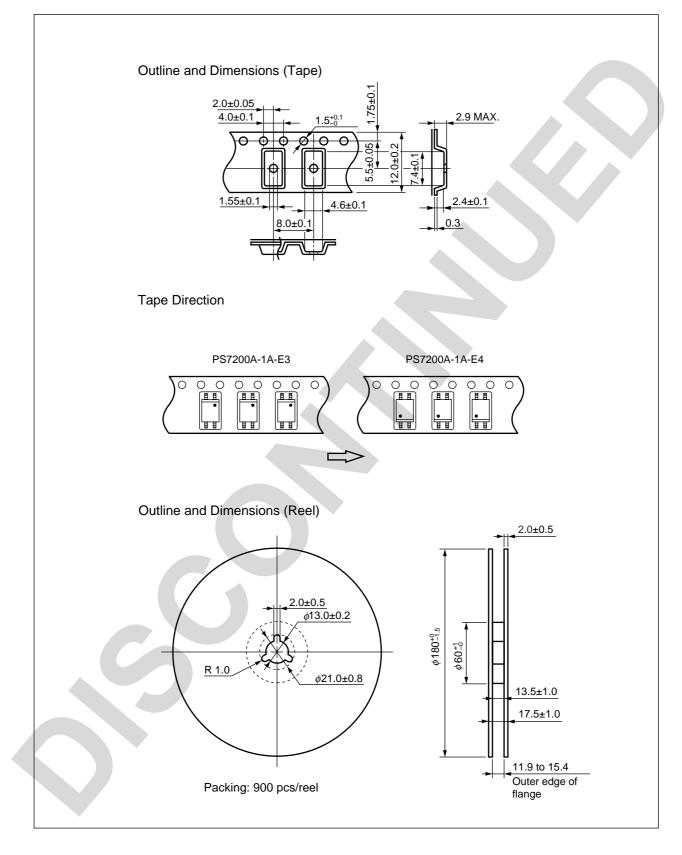


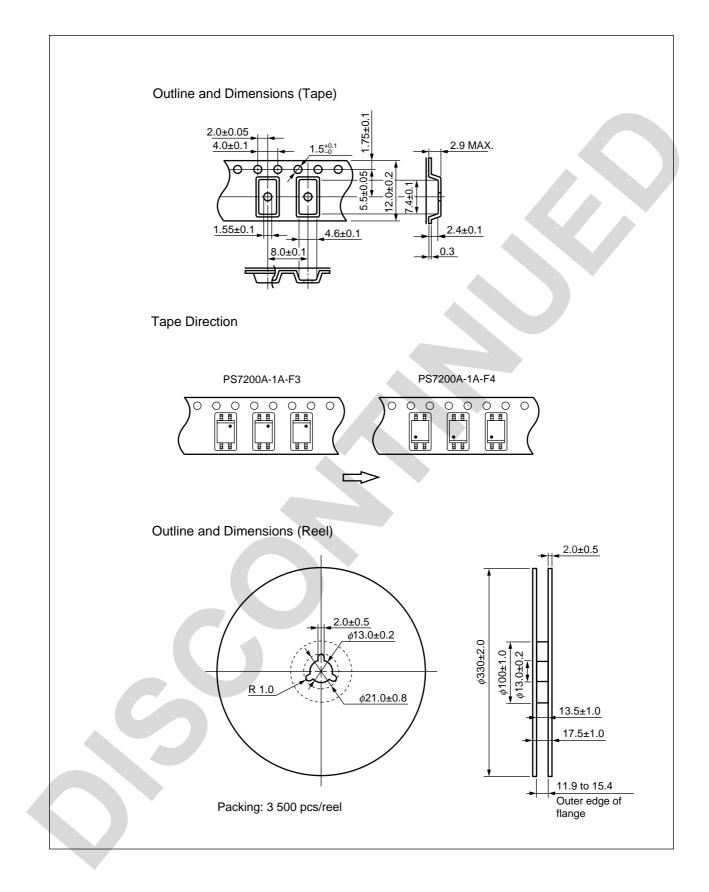




Data Sheet PN10291EJ02V0DS

TAPING SPECIFICATIONS (in millimeters)





RECOMMENDED SOLDERING CONDITIONS

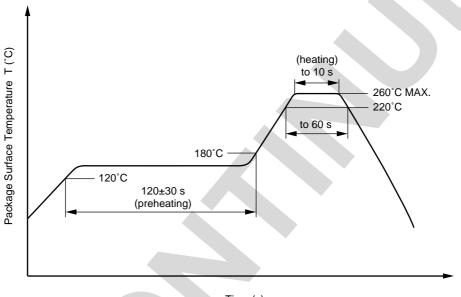
(1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

- Temperature
- Time
 - ne 10 seconds or less eheating conditions 120°C or below (package surface temperature)
- Preheating conditions 120°
 Number of times One
- Number of timesFlux
- Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

 Peak temperature (lead part temperature) 	350°C or below
 Time (each pins) 	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

260°C or below (molten solder temperature)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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